

PMP4448 BOM

Item	Qty	Reference	Description	Size	Value	Part Number	MFR
1	4	C1 C3 C5 C8	Capacitor, Ceramic	0603	NA	STD	muRata
2	1	C6	Capacitor, Ceramic	1210	0.033uF/450V		MuRata
3	1	D2	DIODE FAST RECOVERY 1KV 1A SMA	SMA	RS1M		STD
4	1	D4	DIODE SWITCHING 75V 0.15A SOD323	SOD-323	1N4148WS		STD
5	1	D3	Bridge Rectifier, 600V, 0.8A		HD06		Diodes, Inc
6	1	D1	DIODE ULTRA FAST 600V 2A SMA	SMB	MURA260		STD
7	1	L5	Inductor, EE10		0.8mH	750342750	WE-Midcom
8	1	F1	FUSE BOARD MNT 1A 300VAC RADIAL		1A/250Vac (T)	3691100000	Littlefuse
9	1	E4	VARISTOR 423V 800A DISC 5MM		ERZV05D471		Panasonic
10	1	C2	CAP FILM 0.047UF 400VDC RADIAL		0.047uf		Panasonic
11	1	C12	CAP FILM 0.033UF 400VDC RADIAL		NA		Panasonic
12	1	L1	Radial Leaded Wire Wound Inductor		10mH	744742103	Würth
13	1	C9	Suppression Film Capacitors 0.033uF 305VAC 20%		0.033uF		EPCOS
14	2	R5 R24	Resistor, Chip, 1/10W, 1%	0603	10R	STD	STD
15	1	R3	Resistor, Chip, 1/10W, 1%	0603	33K	STD	STD
16	1	R8	Resistor, Chip, 1/8W, 1%	0805	470K	STD	STD
17	1	R9	Resistor, Chip, 1/10W, 1%	0603	47K	STD	STD
18	1	R13	Resistor, Chip, 1/10W, 1%	0603	51K	STD	STD
19	1	R10	Resistor, Chip, 1/10W, 1%	0603	6.8K	STD	STD
20	1	R14	Resistor, Chip, 1/8W, 1%	0805	1R	STD	STD
21	1	R15	Resistor, Chip, 1/8W, 1%	0805	2R	STD	STD
22	1	R16	Resistor, 1206, 1/4W, 1%	1206	NA	STD	STD
23	2	R6-7	Resistor, Chip, 1/4W, 1%	1206	100K	STD	STD
24	1	C7	CAP ALUM 33UF 10V 20% RADIAL	5mm(D)x7mm(H)	33uF/10V		Panasonic
25	1	C4	CAP ALUM 33UF 35V 20% RADIAL	5mm(D)x12mm(H)	33uF/35V		Panasonic
26	1	C11	CAP ALUM 470UF 50V 20% RADIAL	12.5mm(D)x20mm(H)	470uF/50V		Panasonic
27	1	U1	Primary current sense controller	SO-8	TPS92314A	TPS92314A	TI
28	1	Q1	MOSFET N-CH 600V 1.4A IPAK	TO-220		STD2NK60Z-1	ST
29	1	D6	Diode, Zener, 33V, 400mW, SOD-123	SOD-123	33V	STD	STD
30	4	L LED+ LED- N					STD

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